

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT5283964

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUNG-LIANG CHENG	01/03/2018
YU-LIN LIU	03/31/2018
MING-HSIEN LIN	01/11/2018
TZO-HUNG LUO	01/11/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16220247
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2017-1272/24061.3627US02
NAME OF SUBMITTER:	LINDA INGRAM
SIGNATURE:	/Linda Ingram/
DATE SIGNED:	12/14/2018
Total Attachments: 4	

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Docket No.: P20171272US00/24061.3627US01
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-------------------|----|--------------------------------------|
| (1) | Chung-Liang Cheng | of | Changhua County 500, Taiwan (R.O.C.) |
| (2) | Yu-Lin Liu | of | Hsinchu, Taiwan (R.O.C.) |
| (3) | Ming-Hsien Lin | of | Hsinchu, Taiwan (R.O.C.) |
| (4) | Tzo-Hung Luo | of | Taichung City 40676, Taiwan (R.O.C.) |

have invented certain improvements in

ATOMIC LAYER DEPOSITION BASED PROCESS FOR CONTACT BARRIER LAYER

for which we have executed an application for Letters Patent of the United States of America,

 X of even date filed herewith; and
 filed on 11/16/2017 and assigned application number 15/815,059; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and

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Customer No.: 000042717

testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chung-Liang Cheng

Residence Address: No. 259, Chenleng Rd.
Changhua County 500, Taiwan (R.O.C.)

Dated: 2018/01/03

Chung-Liang Cheng
Inventor Signature

Inventor Name: Yu-Lin Liu

Residence Address: No. 8, Li-Hsin Rd. 6
Hsinchu, Taiwan (R.O.C.)

Dated: _____

Inventor Signature

Inventor Name: Ming-Hsien Lin

Residence Address: No. 8, Li-Hsin Rd. 6
Hsinchu, Taiwan (R.O.C.)

Dated: 2018/01/11

Ming-Hsien Lin
Inventor Signature

Inventor Name: Tzo-Hung Luo

Residence Address: No. 80-10, Dapeng Rd., Beitun Dist.
Taichung City 40676, Taiwan (R.O.C.)

Dated: 2018/01/11
Tzo-Hung Luo

Tzo-Hung Luo
Inventor Signature

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NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chung-Liang Cheng

Residence Address: No. 259, Chenleng Rd.
Changhua County 500, Taiwan (R.O.C.)

Dated: _____

Inventor Signature

Inventor Name: Yu-Lin Liu

Residence Address: No. 8, Li-Hsin Rd. 6
Hsinchu, Taiwan (R.O.C.)

Dated: 2018.3.31

Yu-Lin Liu

Inventor Signature

Inventor Name: Ming-Hsien Lin

Residence Address: No. 8, Li-Hsin Rd. 6
Hsinchu, Taiwan (R.O.C.)

Dated: _____

Inventor Signature

Inventor Name: Tzo-Hung Luo

Residence Address: No. 80-10, Dapeng Rd., Beitun Dist.
Taichung City 40676, Taiwan (R.O.C.)

Dated: _____

Inventor Signature